In the Claims:

Please amend the claims as indicated hereafter.

1-16. (Canceled)

17. (Currently Amended) A device, comprising:

a first substrate;

a second substrate; and

a compliant element of a first, compliant material between said first substrate and said second substrate, said compliant element comprising a side surface coated at least in part with a layer of a second material, said compliant element exhibiting deformation consistent with said first substrate and a second side having been pressed together, wherein said layer of said second material provides said compliant element with a greater hermeticity than said first material alone and wherein said compliant element provides a hermetic seal for a chamber within said device.

18. (Currently Amended) The device of claim 17, wherein said first, compliant material comprises a polymer.

19. (Currently Amended) The device of claim 17, wherein said first, compliant material comprises a polyimide.

20. (Currently Amended) The device of claim 17, wherein said layer of said second material provides said compliant element with greater electrical conductivity than said first, compliant material alone.

21. (Canceled)

22. (Original) The device of claim 17, further comprising a non-compliant spacer pressed between said first and second substrates.

23. (Currently Amended) A device, comprising:

a first substrate;

a second substrate; and

a compliant ~~element~~ gasket between said first substrate and said second substrate, said compliant gasket coated with a hermeticity-increasing layer and exhibiting deformation consistent with said first substrate and said second substrate having been pressed together.

24. (Currently Amended) The device of claim 23, wherein said compliant gasket comprises a polyimide.

25. (New) The device of claim 23, wherein said compliant gasket comprises a polymer.

26. (New) The device of claim 23, wherein said hermeticity-increasing layer is electrically conductive.

27. (New) The device of claim 23, wherein said hermeticity-increasing layer is not electrically conductive.

28. (New) The device of claim 17, wherein said second material is electrically conductive.

29. (New) The device of claim 17, wherein said second material is not electrically conductive.

30. (New) A device, comprising:

a first substrate;

a second substrate; and

a compliant gasket between said first and second substrates, said compliant gasket exhibiting deformation consistent with said first and second substrates having been pressed together, said compliant gasket having a surface coated at least in part with a hermeticity-increasing layer such that said compliant gasket provides a hermetic seal for a chamber between said first and second substrates.

31. (New) The device of claim 30, wherein said compliant gasket comprises a polyimide.

32. (New) The device of claim 30, wherein said compliant gasket comprises a polymer.

33. (New) The device of claim 30, wherein said hermeticity-increasing layer is electrically conductive.

34. (New) The device of claim 30, wherein said hermeticity-increasing layer is not electrically conductive.